CR329 #5 8/2/96 mp

Attorney Docket No. 95-553-US

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OCT 29 1996

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

GROUP 3200

Title of the Invention:

PROBE CARD ASSEMBLY AND KIT, AND METHODS OF USING SAME

Inventors: ELDRIDGE, et al.

Filing Date: November 9, 1995

Serial Number: 08/554,902

SUPPLEMENTAL INFORMATION DISCLOSURE CITATION
(Substitute PTO-1449)

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION is being submitted **prior to an action on the merits.**

NO FEE IS REQUIRED.

Charge any shortfall to Dep. Acct. 12-1445.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION (5) is being provided in addition to:

(1) INFORMATION DISCLOSURE CITATION, filed 4/4/96
(2) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
(3) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96
(4) SUPPLEMENTAL INFORMATION DISCLOSURE CITATION, filed 4/4/96

Although not required, TITLES for the patent references are provided herewith, as an aid to the examiner.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION lists references cited in the International Search Reports pertaining to various commonly-owned, copending PCT applications. All the references listed in the Search Reports are listed herein. However, if the references have previously been disclosed, only the patent number is listed.

This SUPPLEMENTAL INFORMATION DISCLOSURE CITATION also lists references which recently have come to the applicant's attention.

The references presented herein are arranged in "groups", as follows:

GROUP 1. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14909 filed 13 Nov 95.**

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

_x_ copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/452,255, filed 5/26/95**

GROUP 2. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14843 filed 13 Nov 95.**

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

_x_ copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/526,246, filed 9/21/95**

GROUP 3. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14842 filed 13 Nov 95.**

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

_x_ copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/533,584, filed 10/18/95**

GROUP 4. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14844 filed 13 Nov 95.**

_x_ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

___ copies of these references are NOT enclosed herewith,

but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/554,902, filed 11/9/95**

GROUP 5. References related to making pressure connections and resilient contact structures. These references were cited in the International Search Report pertaining to commonly-owned, copending **PCT/US95/14885 filed 15 Nov 95**.

___ copies of these references are enclosed herewith, except for copies of references previously submitted to the Patent Office;

_x_ copies of these references are NOT enclosed herewith, but have (i) previously been disclosed or (ii) may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/558,332, filed 11/15/95**

GROUP 6. References which recently have come to the attention of the applicant.

___ copies of these references are enclosed herewith.

_x_ copies of these references are NOT enclosed herewith, but may be found in the file of commonly-owned, copending U.S. Patent Application No. **08/340,144, filed 11/15/94**

SHOULD THE EXAMINER DESIRE COPIES OF ANY REFERENCES CITED HEREIN, OR IN PREVIOUS INFORMATION DISCLOSURE CITATIONS, APPLICANT WILL PROVIDE SAME UPON REQUEST.

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GROUP 1: PCT/US95/14909 filed 13 Nov 95

5,037,023 Akiyama, et al.; 8/91 228/102
METHOD AND APPARATUS FOR WIREBONDING

5,210,939 Mallik, et al.; 5/93 29/840
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METHOD OF THERMAL DIFFUSION ALLOY PLATING FOR STEEL WIRE ON CONTINUOUS BASIS

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DEVICE FOR INTERCONNECTING INTEGRATED CIRCUIT PACKAGES TO CIRCUIT BOARDS

5,045,975 Cray, et al.; 9/91 361/412
THREE DIMENSIONALLY INTERCONNECTED MODULE ASSEMBLY

3,753,665 McCary, et al.; 8/73 29/191.6
MAGNETIC FILM PLATED WIRE

3,844,909 McCary, et al.; 10/74 204/40
MAGNETIC FILM PLATED WIRE AND SUBSTRATES THEREFOR

4,998,885 Beaman; 3/91 439/66
ELASTOMERIC AREA ARRAY INTERPOSER

JAP 3-142847 (64-279696); 10/89
SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

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GROUP 3: PCT/US95/14842 filed 13 Nov 95

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ELECTRICAL INTERCONNECT USING PARTICLE ENHANCED JOINING OF METAL SURFACES

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5,455,390 DiStefano, et al.; 10/95 174/262
MICROELECTRONICS UNIT MOUNTING WITH MULTIPLE LEAD BONDING

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